

SOT1444-10

WLCSP49, wafer level chip-scale package; 49 bumps; 2.97 mm x 3.37 mm x 0.56 mm (backside coating included)

9 January 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	6-1-2017
Manufacturer package code	SOT1444

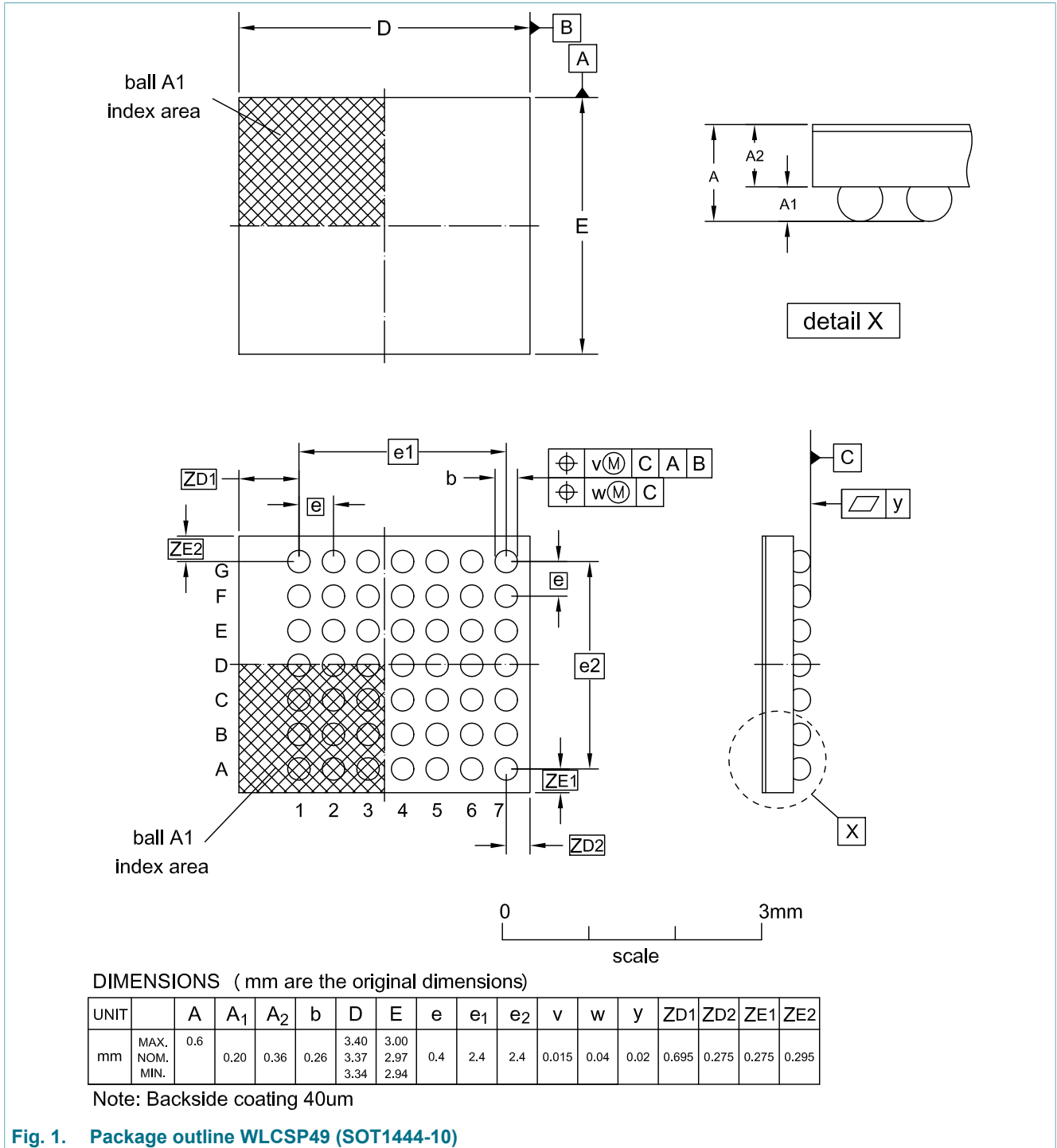
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.34	-	3.37	3.4	mm
E	package width	2.94	-	2.97	3	mm
A	seated height	-	-	-	0.6	mm
A ₂	package height	-	-	0.36	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



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2. Package outline



WLCSP49, wafer level chip-scale package; 49 bumps; 2.97 mm x 3.37 mm x 0.56 mm (backside coating included)

3. Legal information

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